

**Amendments to the Claims:**

Please amend claims 43 and 48 as follows:

Claims 1-24 (Cancelled).

25. (Previously Presented) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:

a carrier;

a release layer located on said carrier, said release layer being etchable; and

a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein said microbeams are releasable from said carrier by at least partially etching away said release layer.

26. (Previously Presented) A microbeam assembly according to Claim 25 wherein the carrier is a tape automated bonding (TAB) carrier and said release layer is formed from a material selected from the group consisting of polyimide and parylene.

27. (Original) A microbeam assembly according to Claim 25, wherein the carrier is substantially rigid.

28. (Original) A microbeam assembly according to Claim 25, wherein the carrier comprises fan-out conductors for electrical testing of an integrated circuit.

29. (Cancelled).

30. (Cancelled).

31. (Original) A microbeam assembly according to Claim 25 wherein at least one microbeam comprises a bump.

32. (Original) A microbeam assembly according to Claim 31 wherein the bump is comprised of solder.

33. (Cancelled).

34. (Original) A microbeam assembly according to Claim 31 wherein the bump is comprised of gold.

35. (Original) A microbeam assembly according to Claim 31 wherein the bump is comprised of aluminum.

36. (Original) A microbeam assembly according to Claim 32 wherein the at least one microbeam further comprises a solder dam.

37. (Original) A microbeam assembly according to Claim 25, wherein the release layer comprises an oxide.

38. (Original) A microbeam assembly according to Claim 25, wherein the release layer comprises glass.

39. (Original) A microbeam assembly according to Claim 28, wherein said fan-out conductors are located on a first region of said carrier and said release layer is located on a second regions of said carrier, wherein said conductive microbeams are releasably bonded to said release layer and are in electrical communication with said fan-out conductors for electrical testing of an integrated circuit connected to the microbeams.

40. (Original) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:  
a carrier;  
a release layer located on said carrier, said release layer comprising an oxidized metal;  
and

a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit.

41. (Original) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:  
a carrier;  
a release layer located on said carrier, said release layer comprising an oxide; and  
a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit.

42. (Original) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:  
a carrier;  
a release layer located on said carrier, said release layer comprising glass; and  
a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit.

43. (Currently Amended) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:  
a carrier;  
a plurality of fan-out conductors located on a first region of said carrier;  
a release layer located on a second region of said carrier;  
a plurality of conductive microbeams located on said release layer, wherein each of said ~~conductor~~-microbeams is in electrical communication with at least one of said fan-out conductors.

44. (Original) A microbeam assembly according to Claim 43, wherein said fan-out connectors are located on a first region of said carrier and said release layer is located on a second region of said carrier and at least partially surrounds said fan-out connectors.

45. (Original) A microbeam assembly according to Claim 43, wherein at least one of said conductive microbeams is located on said release layer and extends at least partially onto one of said fan-out conductors.

46. (Original) A microbeam assembly according to Claim 43, wherein at least one of said fan-out conductors is adjacent to said release layer and at least one of said conductive microbeams is located on said release layer and extends at least partially onto one of said fan-out conductors.

47. (Original) A microbeam assembly according to Claim 43, wherein said release layer is etchable and said microbeams being releasable from said carrier by at least partially etching away said release layer.

48. (Currently Amended) A microbeam assembly according to Claim 43 wherein the carrier is a tape automated bonding (TAB) carrier and said release layer is formed from a material selected from the group consisting of polyimide and parylene.

49. (Original) A microbeam assembly according to Claim 43, wherein the release layer comprises tungsten.

50. (Original) A microbeam assembly according to Claim 43, wherein the release layer comprises an oxidized metal.

51. (Original) A microbeam assembly according to Claim 43, wherein the release layer comprises an oxide.

52. (Original) A microbeam assembly according to Claim 43, wherein the release layer comprises glass.